



Material Content Data Sheet



Sales Product Name		TLE9251LE		Issued		31. July 2018		
MA#		MA001990806						
Package		PG-TSON-8-1		Weight*		26.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.790	2.94	2.94	29402	29402
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		439	
	non noble metal	iron	7439-89-6	0.236	0.88		8790	
wire	non noble metal	copper	7440-50-8	9.586	35.69	36.62	356900	366239
	non noble metal	copper	7440-50-8	0.040	0.15	0.15	1472	1472
	organic material	carbon black	1333-86-4	0.031	0.11		1142	
encapsulation	plastics	epoxy resin	-	1.580	5.88		58837	
	inorganic material	silicondioxide	60676-86-0	13.732	51.13	57.12	511253	571232
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14230	14230
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1618	1618
glue	plastics	epoxy resin	-	0.106	0.40		3952	
	noble metal	silver	7440-22-4	0.318	1.19	1.59	11855	15807
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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